

N-Channel 110V MOSFET

Product summary

V_{DS} (V)	$R_{DS(on),max}$ (m Ω)	I_D (A)
110	2.0 @ $V_{GS} = 10V$	256 ⁽¹⁾

Features

- Low $R_{DS(on)}$ SGT technology
- Low thermal impedance
- Fast switching speed
- 100% avalanche tested

Applications

- DC/DC conversion
- Power switch
- Motor drives

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Package and ordering information

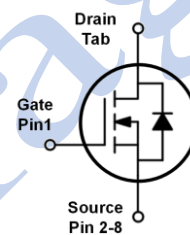
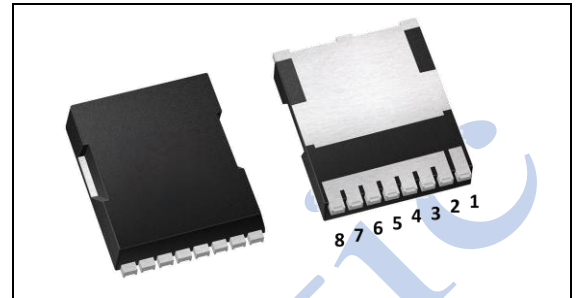
Ordering code	Package	Device code
SDN11N002T-AA	TOLL	ALB

1. Maximum ratings

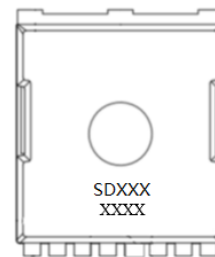
Absolute maximum ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source voltage		V_{DS}	110	V
Gate-source voltage		V_{GS}	± 20	
Continuous drain current	$T_C = 25^\circ\text{C}$ ⁽¹⁾	I_D	256	A
	$T_C = 100^\circ\text{C}$		162	
	$T_A = 25^\circ\text{C}$ ⁽⁴⁾		29	
Pulsed drain current ⁽²⁾		$I_{D,pulse}$	1024	
Avalanche energy, single pulse ⁽³⁾		E_{AS}	278	mJ
Power dissipation	$T_C = 25^\circ\text{C}$	P_D	250	W
	$T_A = 25^\circ\text{C}$ ⁽⁴⁾		3.1	
Operating junction and storage temperature range		T_J, T_{stg}	-55 to 150	$^\circ\text{C}$

TOLL



RoHS
COMPLIANT
HALOGEN
FREE



SDXXX
└─ Device code
└─ Silicon Magic discrete device

XXXX
└─ Wafer lot number
└─ Work week code
└─ Year code

2. Thermal resistance ratings

Thermal resistance ratings				
Parameter		Symbol	Max.	Unit
Thermal resistance, junction-to-case	Steady state	$R_{\theta JC}$	0.5	°C/W
Thermal resistance, junction-to-ambient ⁽⁴⁾	Steady state	$R_{\theta JA}$	40	

3. Electrical Characteristics

Electrical characteristics (T _j = 25°C unless otherwise noted)						
Parameter	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Static parameter						
Drain to source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 1 mA	110			V
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	2.5	3.3	4.1	V
Gate-body leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±20 V			±100	nA
Zero gate voltage drain current	I _{DSS}	V _{DS} = 105 V, V _{GS} = 0 V			1	μA
Drain-source on-resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 100 A		1.6	2	mΩ
Forward transconductance ⁽⁵⁾	g _{fs}	V _{DS} = 5 V, I _D = 100 A		270		S
Gate resistance	R _g	f = 1 MHz		1.9		Ω
Dynamic ⁽⁵⁾						
Total gate charge	Q _g	V _{DS} = 50 V, I _D = 100 A, V _{GS} = 10 V		145		nC
Gate-source charge	Q _{gs}			49		
Gate-drain charge	Q _{gd}			45		
Turn-on delay time	t _{d(on)}	V _{DS} = 50 V, I _D = 100 A, V _{GS} = 10 V, R _{GEN} = 6 Ω		103		ns
Rise time	t _r			142		
Turn-off delay time	t _{d(off)}			65		
Fall time	t _f			74		
Input capacitance	C _{iss}	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz		8800		pF
Output capacitance	C _{oss}			2200		
Reverse transfer capacitance	C _{rss}			89		
Reverse Diode Characteristics ⁽⁵⁾						
Diode forward voltage	V _{SD}	V _{GS} = 0 V, I _F = 100 A		0.9	1.2	V
Reverse recovery time	t _{rr}	V _{DS} = 50 V, I _F = 50 A, di/dt = 100 A/μs		88		ns
Reverse recovery charge	Q _{rr}			175		nC

Notes

- (1) Limited by maximum junction temperature..
- (2) Pulse width limited by maximum junction temperature.
- (3) $V_{DS} = 50\text{ V}, V_{GS} = 10\text{ V}, L = 0.1\text{ mH}$.
- (4) $R_{\theta JA}$ is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5x1.5 in. board of FR-4 material.
- (5) Guaranteed by design, not subject to production testing.

4. Electrical characteristics diagrams

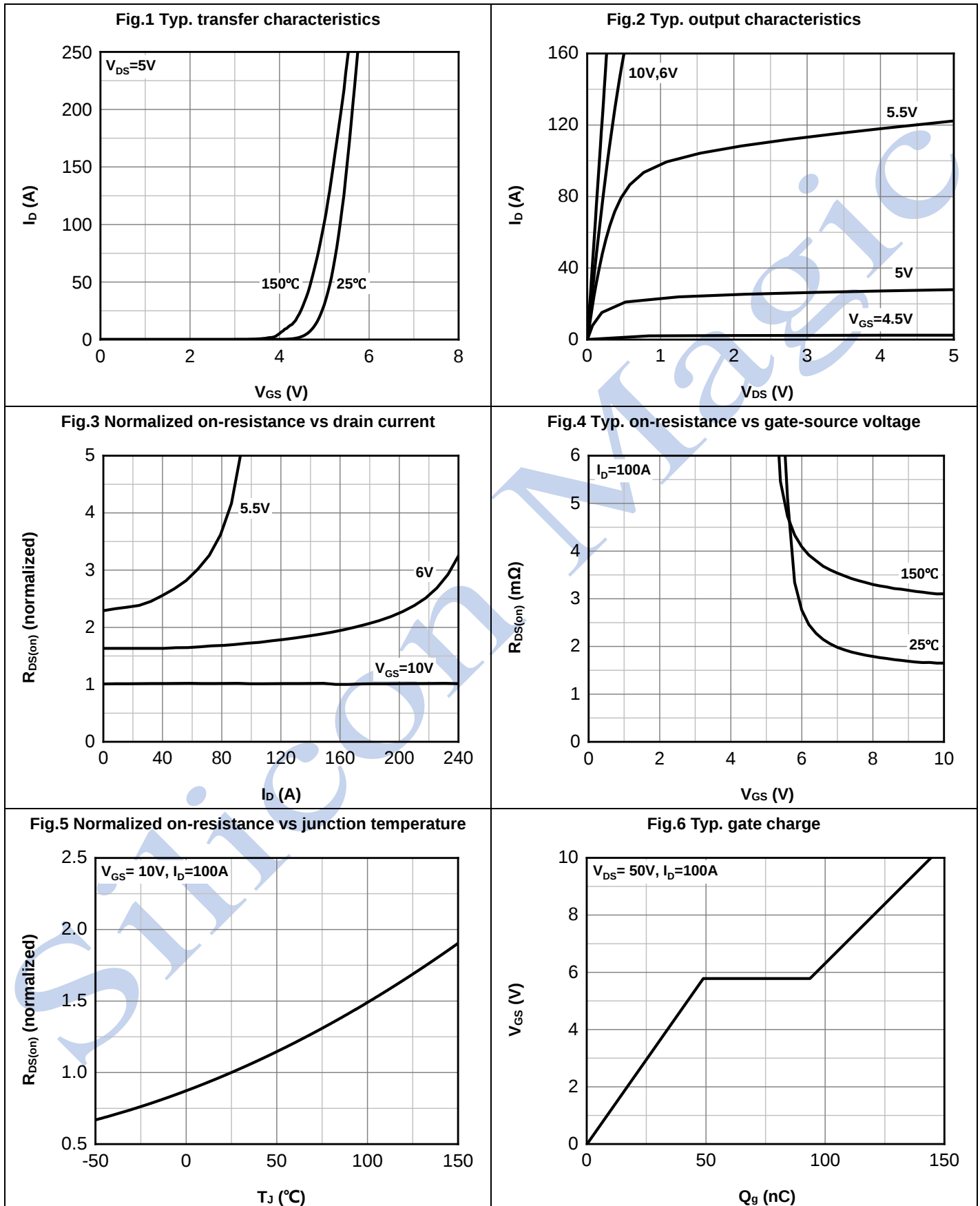


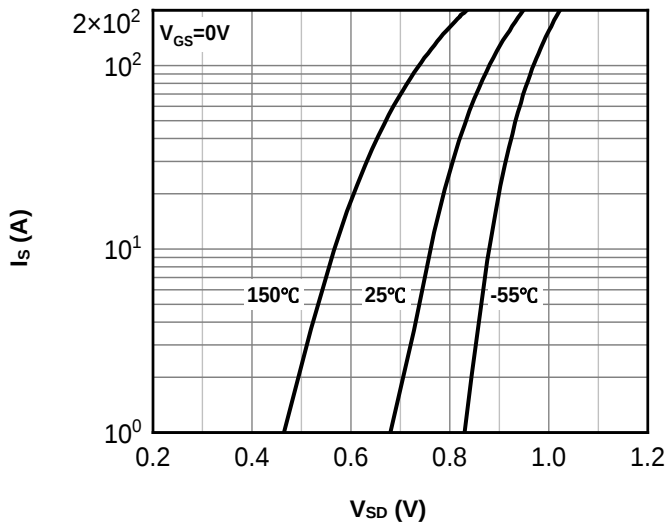
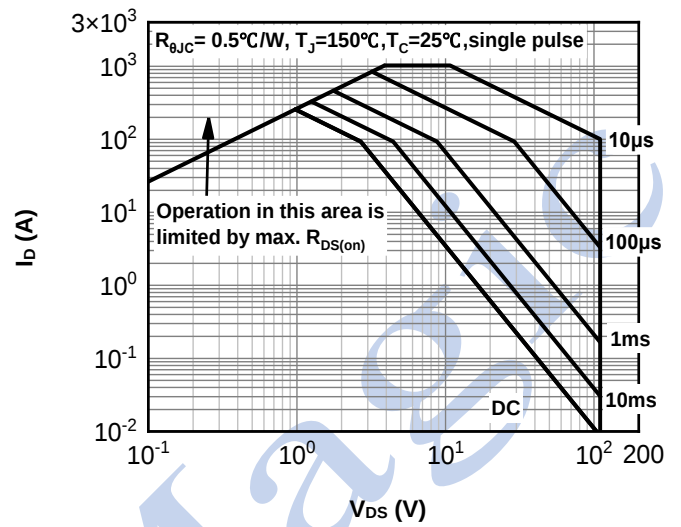
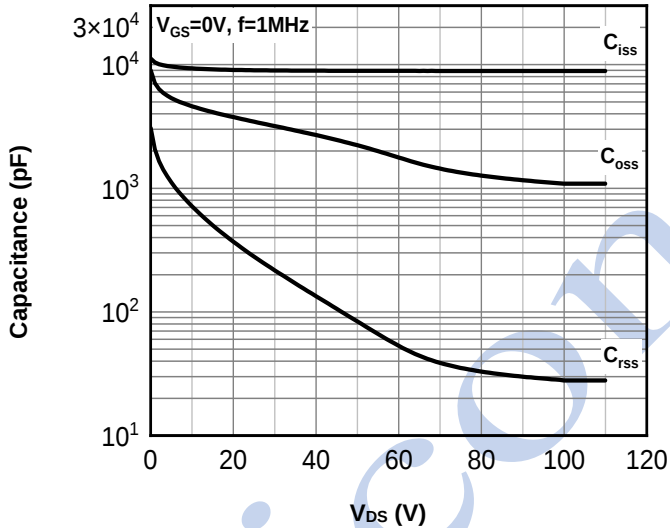
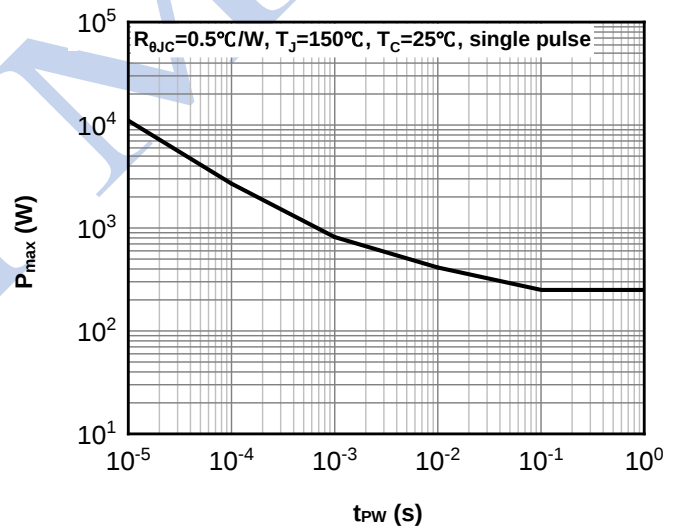
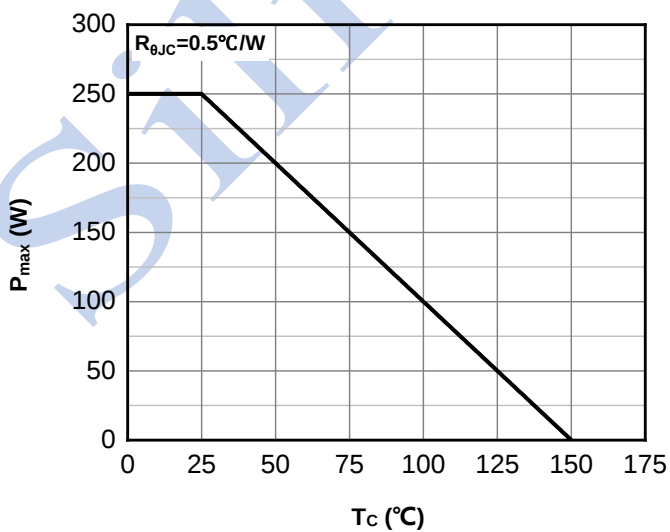
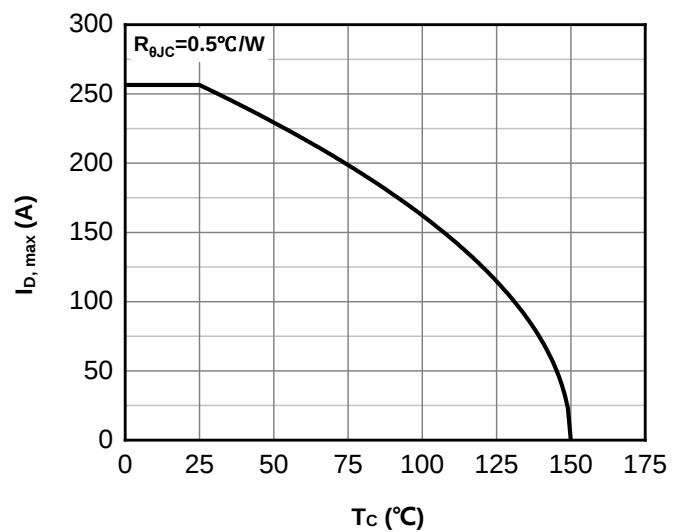
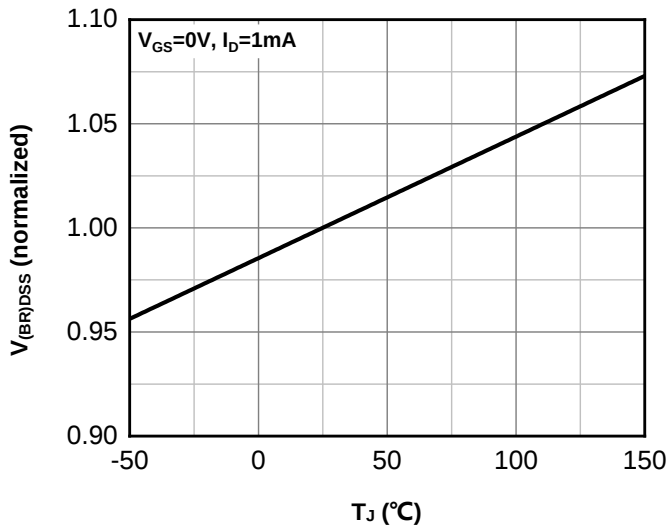
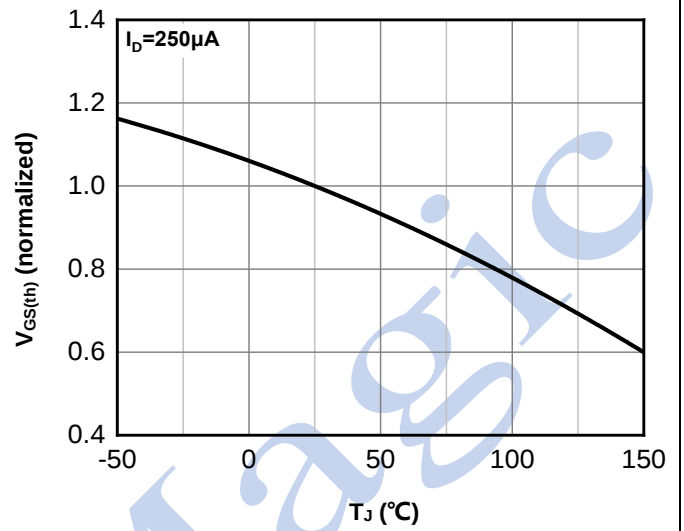
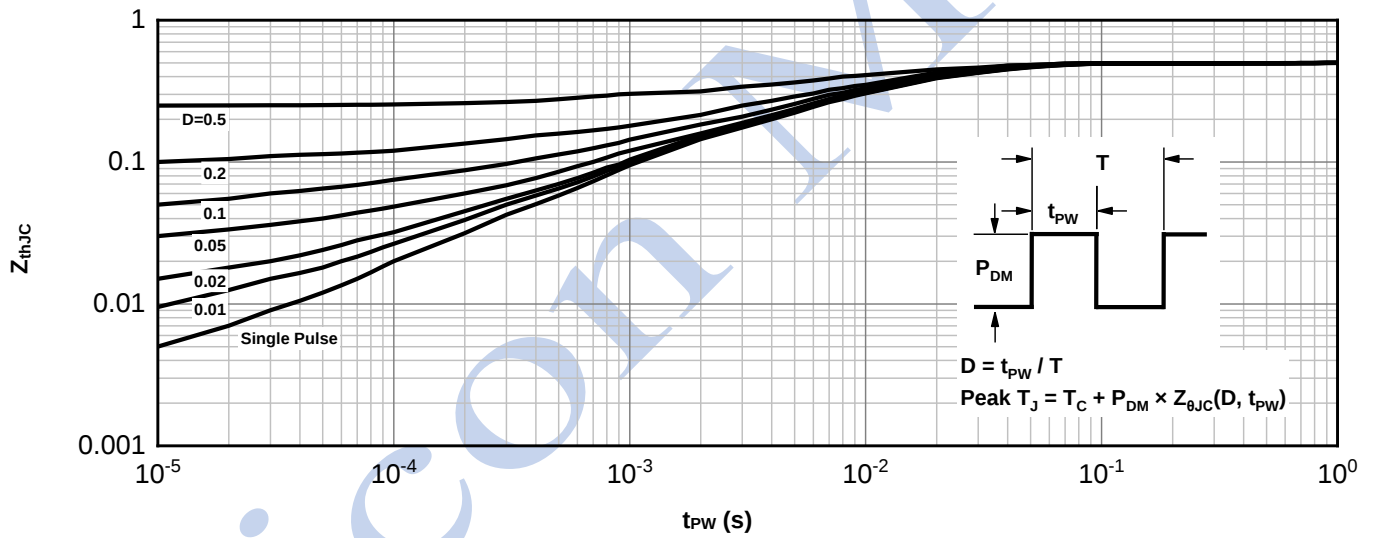
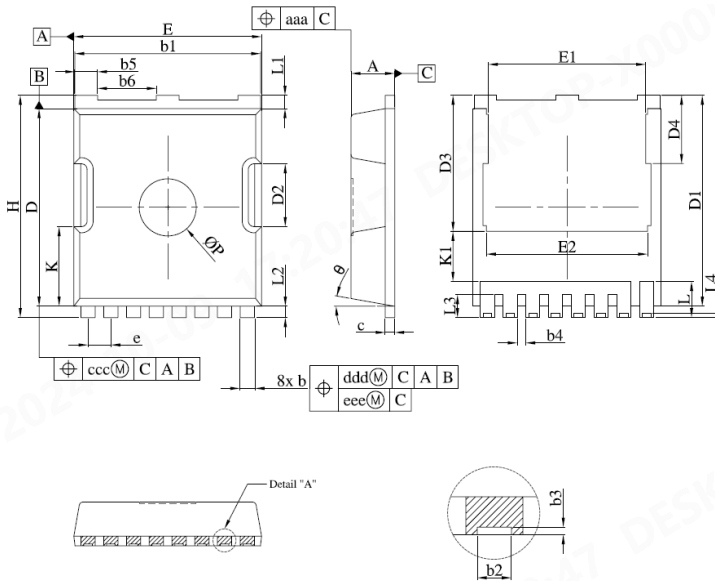
Fig.7 Typ. forward characteristics of body diode

Fig.8 Safe operating area

Fig.9 Typ. Capacitance

Fig.10 Single pulse maximum power dissipation

Fig.11 Max. power dissipation vs case temperature

Fig.12 Max. continuous drain current vs case temperature


Fig.13 Normalized $V_{(BR)DSS}$ vs junction temperature

Fig.14 Normalized $V_{GS(th)}$ vs junction temperature

Fig.15 Transient thermal impedance from junction to case


5. Package outline dimensions



Dim	Millimeters		
	Min	Nom	Max
A	2.20	2.30	2.40
b	0.70	0.80	0.90
b1	9.70	9.80	9.90
b2	0.36	0.45	0.55
b3	0.05	0.10	0.35
b4	0.30	0.40	0.50
b5	1.10	1.20	1.30
b6	3.00	3.10	3.20
c	0.40	0.50	0.60
D	10.28	10.38	10.55
D1	10.98	11.08	11.18
D2	3.20	3.30	3.40
D3	7.00	7.15	7.30
D4	3.44	3.59	3.74
e	1.10	1.20	1.30
E	9.80	9.90	10.00
E1	8.20	8.30	8.40
E2	8.35	8.50	8.65
H	11.50	11.68	11.85
K	4.08	4.18	4.28
K1	2.45	—	—
L	1.60	1.90	2.10
L1	0.50	0.70	0.90
L2	0.50	0.60	0.70
L3	1.00	1.20	1.30
L4	0.13	0.23	0.33
P	2.85	3.00	3.15
φ	10° REF		
aaa	0.20		
ccc	0.20		
ddd	0.25		
eee	0.20		

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